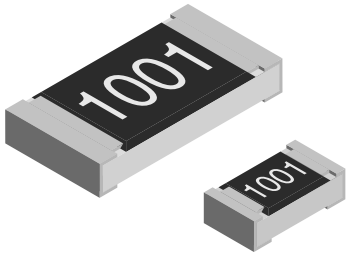
Lead (Pb)-Free Thick Film, Rectangular, Semi-Precision Chip Resistors



FEATURES

- Low temperature coefficient (50 ppm/K) and tight tolerances (± 0.25 %)
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processing
- Metal glaze on high quality ceramic
- AEC-Q200 qualified
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT
HALOGEN FREE

STANDARD ELECTRICAL SPECIFICATIONS

MODEL	CASE SIZE INCH	CASE SIZE METRIC	POWER RATING P_{70} W	LIMITING ELEMENT VOLTAGE $U_{max.}$ AC_{RMS}/DC V	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	SERIES
D10/CRCW0402-P	0402	1005	0.063	50	± 100	± 0.5	1R to 1M1	E24; E96
					± 50	± 0.25, ± 0.5, ± 1	100R to 1M	
D11/CRCW0603-P	0603	1608	0.1	75	± 100	± 0.5, ± 0.25	1R to 10M	E24; E96
					± 50	± 0.25	100R to 1M	
						± 0.5, ± 1	100R to 10M	
D12/CRCW0805-P	0805	2012	0.125	150	± 100	± 0.5	10R to 10M	E24; E96
					± 50	± 0.25	100R to 1M	
						± 0.5, ± 1	100R to 10M	
D25/CRCW1206-P	1206	3216	0.25	200	± 100	± 0.5	10R to 10M	E24; E96
					± 50	± 0.25	100R to 1M	
						± 0.5, ± 1	100R to 10M	
CRCW1210-P	1210	3225	0.5	200	± 100	± 0.5	100R to 1M	E24; E96
					± 50	± 0.5, ± 1	100R to 1M	
CRCW1218-P	1218	3246	1.0	200	± 100	± 0.5	100R to 2M2	E24; E96
					± 50	± 0.5, ± 1	100R to 2M2	
CRCW2010-P	2010	5025	0.75	400	± 100	± 0.5	10R to 10M	E24; E96
					± 50	± 0.5, ± 1	100R to 10M	
CRCW2512-P	2512	6332	1.0	500	± 100	± 0.5	10R to 10M	E24; E96
					± 50	± 0.5, ± 1	100R to 10M	

Notes

- These resistors do not feature a limited lifetime when operated within the limits of rated dissipation, permissible operating voltage and permissible film temperature. However, the resistance typically increase due to the resistor's film temperature over operating time generally known as drift. The drift may exceed the stability requirements of an individual application circuit and thereby limits the functional time.
- Marking and packaging: See datasheet "Surface Mount Resistor Marking" (www.vishay.com/doc?20020).
- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material.

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TECHNICAL SPECIFICATIONS

PARAMETER	UNIT	D10/ CRCW0402-P	D11/ CRCW0603-P	D12/ CRCW0805-P	D25/ CRCW1206-P	CRCW1210-P	CRCW1218-P	CRCW2010-P	CRCW2512-P
Rated Dissipation at P_{70} (1)	W	0.063	0.1	0.125	0.25	0.5	1.0	0.75	1.0
Operating Voltage $U_{max.}$ AC_{RMS}/DC	V	50	75	150	200	200	200	400	500
Insulation Voltage U_{ins} (1 min)	V	75	100	200	300	300	300	300	300
Insulation Resistance	Ω	> 10^9							
Operating Temperature Range	°C	- 55 to + 155							
Failure Rate	h^{-1}	< 0.1 x 10^{-9}							
Weight	mg	0.65	2	5.5	10	16	29.5	25.5	40.5

Note

(1) The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-ciruit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.

PART NUMBER AND PRODUCT DESCRIPTION

PART NUMBER: CRCW040275R0DKEDP

C	R	C	W	0	4	0	2	7	5	R	0	D	K	E	D	P

MODEL	RESISTANCE	TOLERANCE	TCR	PACKAGING	SPECIAL
CRCW0402 **CRCW0603** **CRCW0805** **CRCW1206** **CRCW1210** **CRCW1218** **CRCW2010** **CRCW2512**	**R** = Decimal **K** = Thousand **M** = Million	**C** = ± 0.25 % **D** = ± 0.5 % **F** = ± 1.0 %	**H** = ± 50 ppm/K **K** = ± 100 ppm/K	**EA, EB,** **EC, ED,** **EE, EF,** **EG, EH,** **EI, EL** **EK**	**P** = Semi-**Precision**

PRODUCT DESCRIPTION: D10/CRCW0402-P 100 75R 0.5 % ET7 e3

D10/CRCW0402-P	100	75R	0.5 %	ET7	e3
MODEL	TCR	RESISTANCE	TOLERANCE	PACKAGING	LEAD (Pb)-FREE
D10/CRCW0402-P **D11/CRCW0603-P** **D12/CRCW0805-P** **D25/CRCW1206-P** **CRCW1210-P** **CRCW1218-P** **CRCW2010-P** **CRCW2512-P**	**± 50** ppm/K **± 100** ppm/K	**49K9** = 49.9 kΩ **5R1** = 5.1 Ω	**± 0.25 %** **± 0.5 %** **± 1 %**	**ET1, ET2,** **ET3, ET4,** **ET5, ET6,** **ET7, ET8,** **ET9, EF4,** **E02, E67,** **E82**	**e3** = Pure tin termination finish

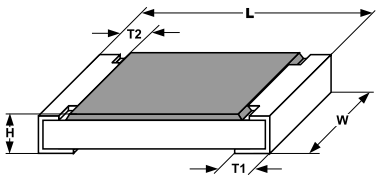
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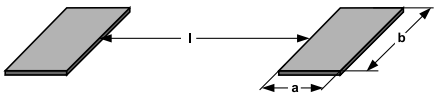
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PACKAGING

MODEL	CODE	QUANTITY	CARRIER TAPE	WIDTH	PITCH	REEL DIAMETER
D10/CRCW0402-P	ED = ET7	10 000	Paper tape acc. to IEC 60068-3 Type I	8 mm	2 mm	180 mm/7"
	EE = EF4	50 000				330 mm/13"
D11/CRCW0603-P	EI = ET2	5000		8 mm	2 mm	180 mm/7"
	ED = ET3	10 000				180 mm/7"
	EL = ET4	20 000				285 mm/11.25"
	EE = ET8	50 000				330 mm/13"
	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
D12/CRCW0805-P	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
D25/CRCW1206-P	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW1210-P	EA = ET1	5000		12 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW1218-P	EK = ET9	4000	Blister tape acc. to IEC 60068-3 Type II	12 mm	4 mm	180 mm/7"
CRCW2010-P	EF = E02	4000		12 mm	4 mm	180 mm/7"
CRCW2512-P	EG = E67	2000		12 mm	8 mm	180 mm/7"
	EH = E82	4000			4 mm	

DIMENSIONS in millimeters



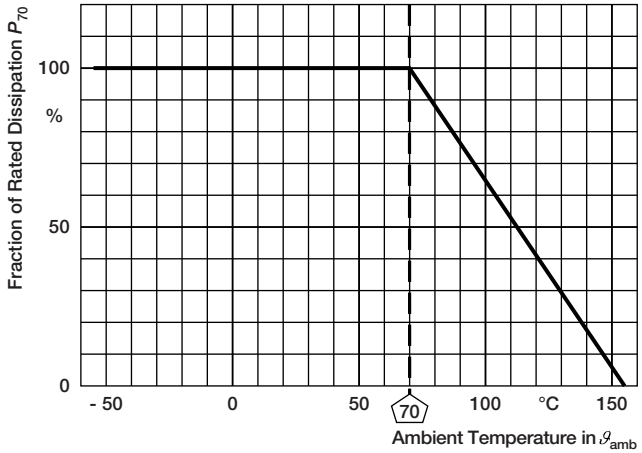


SIZE		DIMENSIONS					SOLDER PAD DIMENSIONS					
							REFLOW SOLDERING			WAVE SOLDERING		
INCH	METRIC	L	W	H	T1	T2	a	b	l	a	b	l
0402	1005	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.25 ± 0.05	0.2 ± 0.1	0.4	0.6	0.5			
0603	1608	1.55 $^{+0.10}_{-0.05}$	0.85 ± 0.1	0.45 ± 0.05	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0
0805	2012	2.0 $^{+0.20}_{-0.10}$	1.25 ± 0.15	0.45 ± 0.05	0.3 $^{+0.20}_{-0.10}$	0.3 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3
1206	3216	3.2 $^{+0.10}_{-0.20}$	1.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	1.7	2.0	1.1	1.7	2.3
1210	3225	3.2 ± 0.2	2.5 ± 0.2	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	2.5	2.0	1.1	2.5	2.2
1218	3246	3.2 $^{+0.10}_{-0.20}$	4.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	1.05	4.9	1.9	1.25	4.8	1.9
2010	5025	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	2.5	3.9	1.2	2.5	3.9
2512	6332	6.3 ± 0.2	3.15 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	3.2	5.2	1.2	3.2	5.2

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FUNCTIONAL PERFORMANCE



TEST PROCEDURES AND REQUIREMENTS

EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
			Stability for product types:	**STABILITY CLASS 1 OR BETTER**
			D/CRCW-P e3	1 Ω to 10 MΩ
4.5	-	Resistance	-	± 0.25 %; ± 0.5 %; ± 1 %
4.7	-	Voltage proof	U = 1.4 x U_{ins}; 60 s	No flashover or breakdown
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R} \leq 2 \times U_{max.}$; duration acc. to style	± (0.25 % R + 0.05 Ω)
4.17.2	58 (Td)	Solderability	Solder bath method; Sn60Pb40 non-activated flux; (235 ± 5) °C (2 ± 0.2) s	Good tinning (≥ 95 % covered) no visible damage
			Solder bath method; Sn96.5Ag3Cu0.5 non-activated flux; (245 ± 5) °C (3 ± 0.3) s	Good tinning (≥ 95 % covered) no visible damage
4.8.4.2	-	Temperature coefficient	(20/- 55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 100 ppm/K
4.32	21 (Uu_3)	Shear (adhesion)	RR 1608 and smaller: 9 N RR 2012 and larger: 45 N	No visible damage
4.33	21 (Uu_1)	Substrate bending	Depth 2 mm; 3 times	No visible damage, no open circuit in bent position ± (0.25 % R + 0.05 Ω)
4.19	14 (Na)	Rapid change of temperature	30 min at - 55 °C; 30 min at 125 °C 5 cycles 1000 cycles	± (0.25 % R + 0.05 Ω) ± (1 % R + 0.05 Ω)

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TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	**IEC 60068-2 TEST METHOD**	**TEST**	**PROCEDURE**	**REQUIREMENTS PERMISSIBLE CHANGE (ΔR)**
			Stability for product types:	**STABILITY CLASS 1 OR BETTER**
			D/CRCW-P e3	1 Ω to 10 MΩ
4.23	-	Climatic sequence:	-	± (1 % R + 0.05 Ω)
4.23.2	2 (Ba)	Dry heat	125 °C; 16 h	
4.23.3	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 % RH; 24 h; 1 cycle	
4.23.4	1 (Aa)	Cold	- 55 °C; 2 h	
4.23.5	13 (M)	Low air pressure	1 kPa; (25 ± 10) °C; 1 h	
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 % RH; 24 h; 5 cycles	
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R}$	
4.25.1	-	Endurance at 70 °C	$U = \sqrt{P_{70} \times R} \leq U_{max.}$; 1.5 h on; 0.5 h off;	
			70 °C; 1000 h	± (1 % R + 0.05 Ω)
			70 °C; 8000 h	± (2 % R + 0.05 Ω)
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s	± (0.25 % R + 0.05 Ω)
4.35	-	Flamability, needle flame test	IEC 60695-11-5; 10 s	No burning after 30 s
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; (93 ± 3) % RH; 56 days	± (1 % R + 0.05 Ω)
4.25.3	-	Endurance at upper category temperature	155 °C, 1000 h	± (1 % R + 0.05 Ω)
4.40	-	Electrostatic discharge (human body model)	IEC 61340-3-1; 3 pos. + 3 neg. discharges; ESD voltage acc. to size	± (1 % R + 0.05 Ω)
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2	No visible damage
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush	Marking legible, no visible damage
4.22	6 (Fc)	Vibration, endurance by sweeping	f = 10 Hz to 2000 Hz; x, y, z ≤ 1.5 mm; A ≤ 200 m/s^2; 10 sweeps per axis	± (0.25 % R + 0.05 Ω)
4.37	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R} \leq 2 \times U_{max.}$; 0.1 s on; 2.5 s off; 1000 cycles	± (1 % R + 0.05 Ω)
4.27	-	Single pulse high voltage overload, 10 µs/700 µs	$\hat{U} = 10 \times \sqrt{P_{70} \times R} \leq 2 \times U_{max.}$; 10 pulses	± (1 % R + 0.05 Ω)

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 140400, sectional specification
- EN 140401-802, detail specification
- IEC 60068-2-x, variety of environmental test procedures

Packaging of components is done in paper or blister tapes according to IEC 60286-3.

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